UF3000ex series Prober Configuration

1.Configuration

Auto loader , Double Load Port
GPIB interface
Self-calibration system
Auto Needle Alignment
Auto Needle Height
Auto pad alignment unit
LCD Display (15 in)
Real Time wafer map display
Multi-site probing function 3-64 dies
Needle Cleaning
Probe Card Holder, RTGR-48
Chuck Type :Nickal12 inch
Offline ink function
Ink check function
Inker device (OPTIONAL)
Needle Inspection
Profiler Sensor
Configuration data

2.PROBER SPECIFICATIONS

1. Power source:
（1）Voltage：AC 220±20V

（2）Consumption： Approximately 3kVA

2. Overall Size：1487W x 1622mm x 967H mm

3. Weight：1650kg (Standard)

4. Mechanical I/F with tester：Rectangular Prober card (cable end type)
5. Total Accuracy：±2μm
6. Chuck Temp: 50~150° C
7. Acceptable wafer dimensions
（1）wafer diameter：Diameter of5",6",8"and12"

（2）thickness：200-1000um

（3）thickness variation：Less than ±50um

8. Max tested die numbers:UF3000EX : 250K DIES

9. Air supply
（1）Pressure：0.4 MPa or more

10. Vacuum supply：Less than 50kPa, 30 liters/minute

11. X/Y axes
（1）Probing area：±170mm
（2）Max Speed：500mm/s
（3）Resolution：0.5um

12. Z axis
（1）Full stroke：37mm
（2）Max Speed：30mm/sec （3）Resolution：3.75um

13. Chuck Z control
（1）Control accuracy：±2um

（2）Overtravel：0~500um
（3）0axis Rotation Range：±4°

（4）Resolution：0.00028°
（5）Fine Alignment：CCD ITV Image Processing

14. Hard Disk Drive

（1）Capacity:40G byte or more

（2）Number of drive:1drive

15. Floppy Disk Drive

（1）Disk nominal size:3.5 inches

（2）Number of drive:1drive

16. USB interface: use of external memory possible

17. Display: 15 inch TFT high color LCD